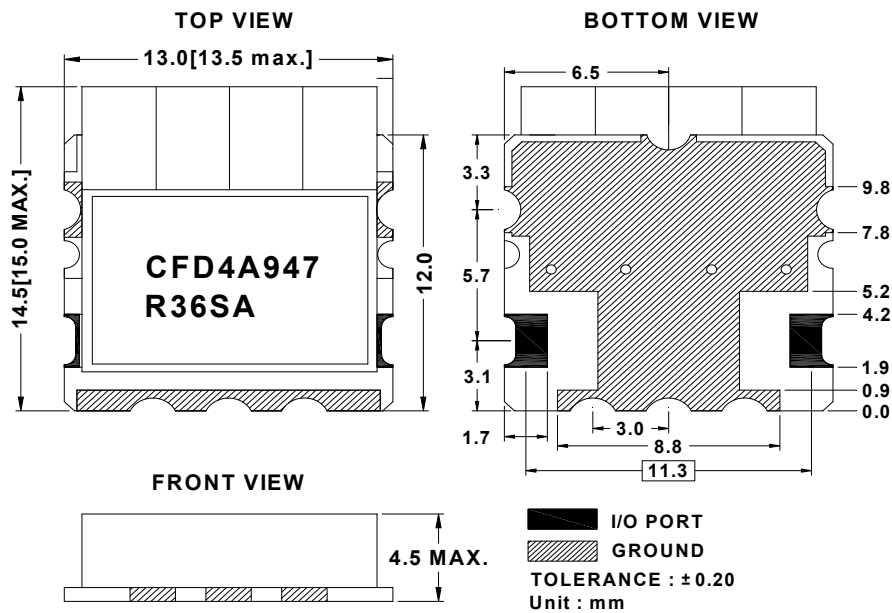


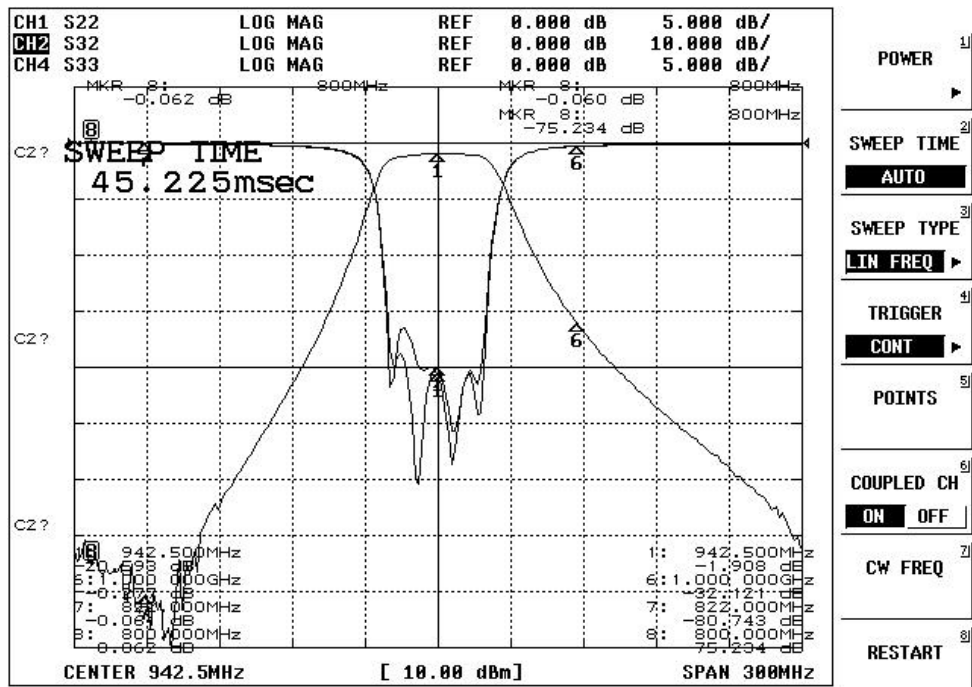
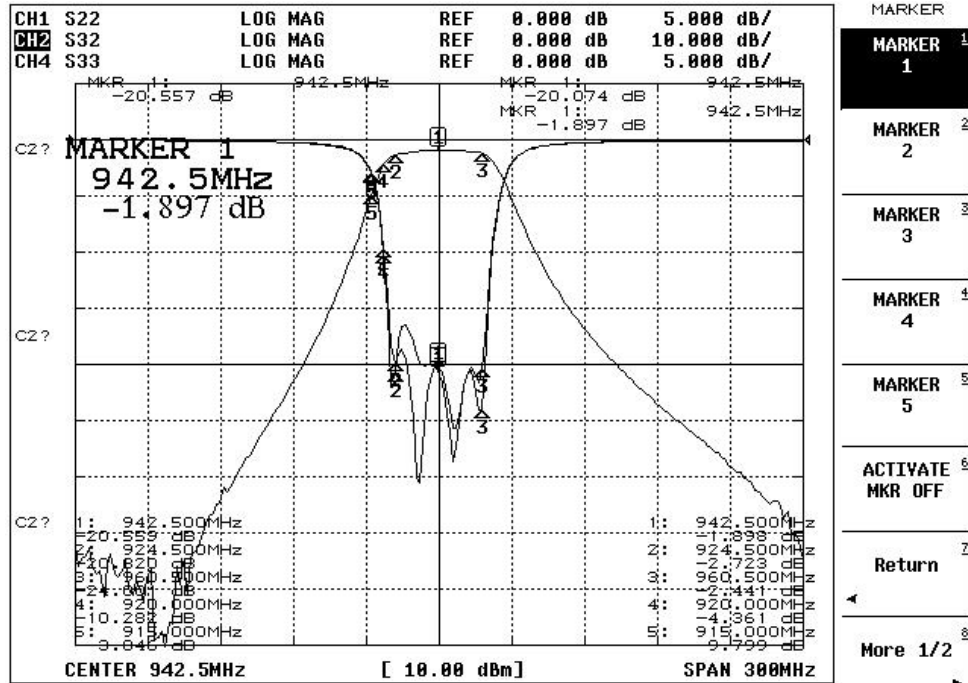
**Electrical Specification**

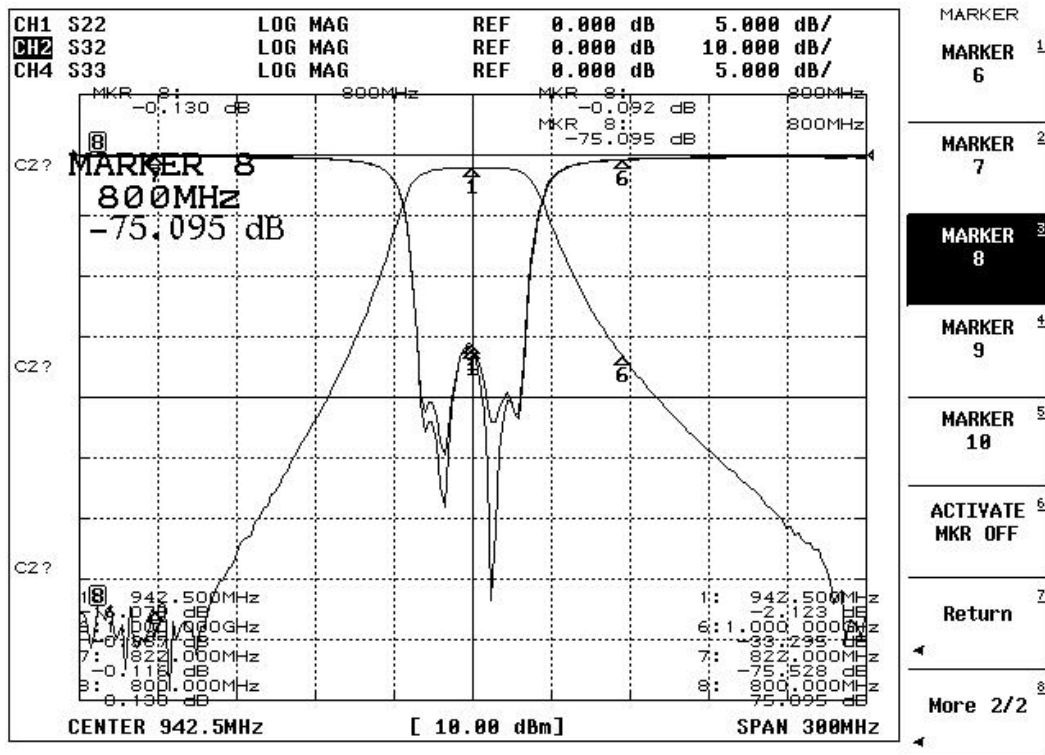
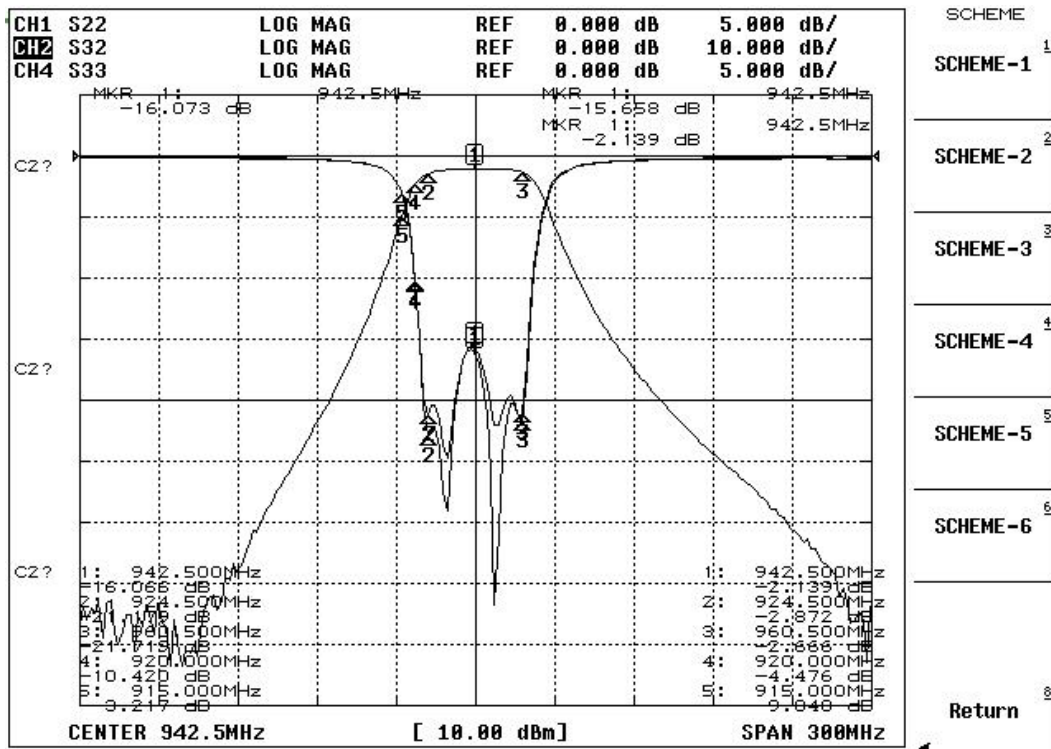
ITEMS	SPEC	UNIT
Center Frequency [fo]	942.0	MHz
Bandwidth [BW]	fo ±18.0 [924.5~960.5]	MHz
Insertion Loss in BW	3.0	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	70.0 dBc min. @ fo ± [300.0 ~ 800.0 ]	MHz
	70.0 dBc min. @ fo ± [822.0 & ]	MHz
	30.0 dBc min. @ fo ± [1000.0 & ]	MHz
	7.0 dBc min. @ fo ± [915 & ]	MHz
	1.5 dBc min. @ fo ± [920 & ]	MHz
	30.0 dBc min. @ fo ± [1050 ~ ]	MHz
	30.0 dBc min. @ fo ± [ & 3000.0]	MHz
Group Delay Variation		MHz
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

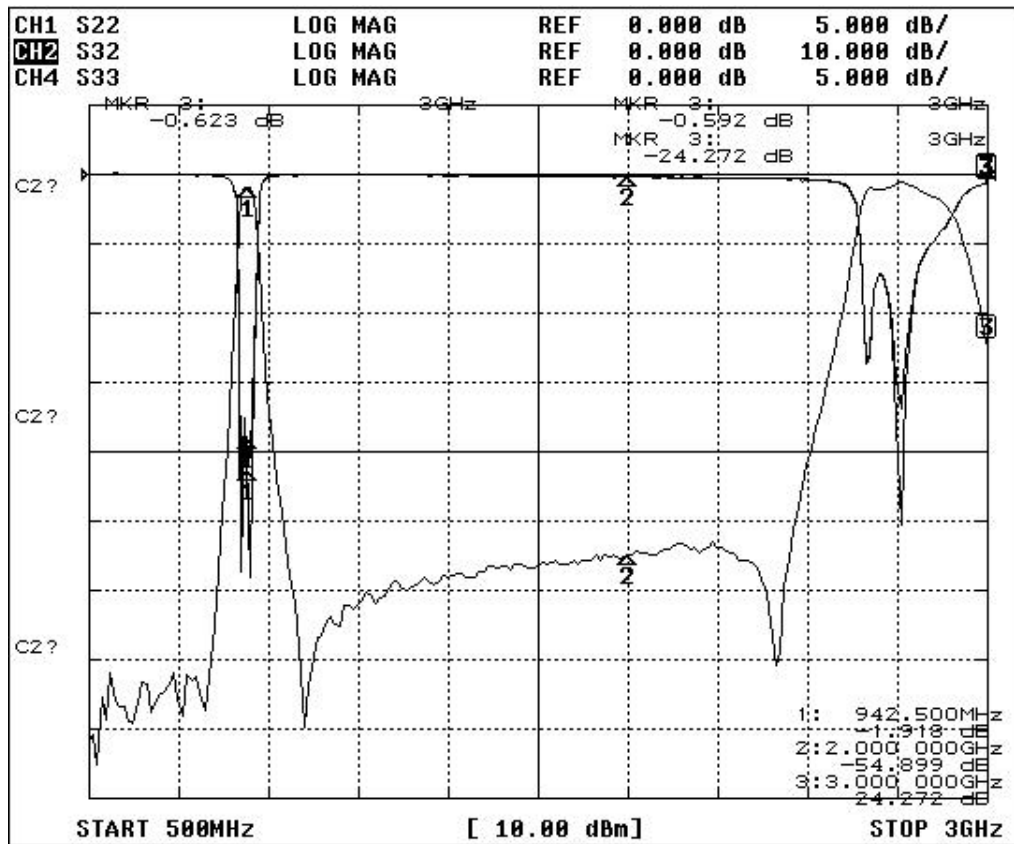
**Mechanical Specification**



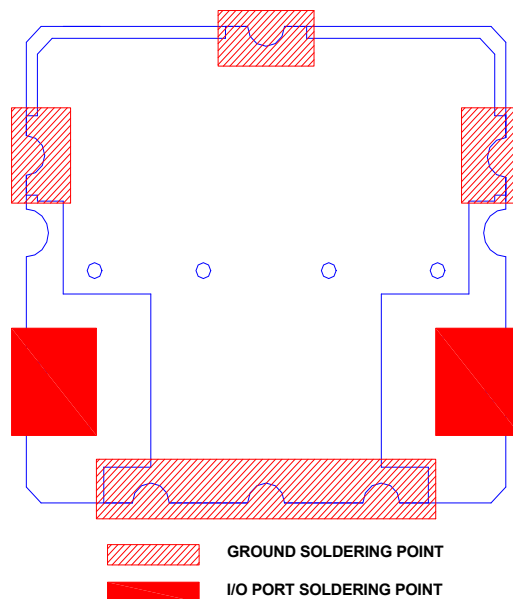
## Plot Data



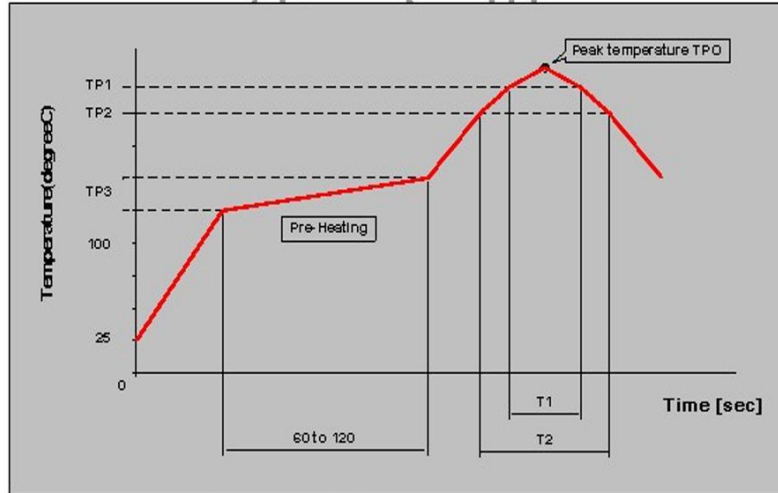




## Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180